

Wafer Level Package Micro WorkCell Series

MWC3000



Wafer Level Package

● Various Process..

Chip stacking,
Die Bonding, Flip Chip, Soldering,
Laser Heating..
Flash memory, CMOS, MicroSD
HDA HSA HGA Canch Lever

Accurate without damage

Bonding accuracy : $\pm 1 \mu\text{m} \sim 15 \mu\text{m}$
UPH : 500~2000
Wafer Size : 100~300mm

Option:

*Loading/unloading by Handling robot

*Dispenser

*Inspection

Travel Range

Pick up stage : X, Y axis/300mm
X linear axis/890 mm
Z axis/30 mm

Alignment stage : θ axis

Placement Stage : X, Y axis/310mm
X linear axis/890mm
Z axis/30mm



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